

INFORMATION DISCLOSURE CITATION
(37 CFR 1.97)

Application Number
Filing Date
First Named Inventor Rutten
Group Art Unit
Examiner Name
Attorney Docket US 018180

J1036 U.S. PTO
10/005689

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U.S. PATENT DOCUMENTS

Examiner's Initials	Cite No.	Patent Number	Date	Name	Class	Sub-Class	Filing Date, if Approp.
21	AA	6,075,373	13 June 2000	Iino			
	AB	6,169,410 B1	2 January 2001	Grace et al.			
	AC	(copending application) "PRECONDITIONED INTEGRATED CIRCUIT FOR INTEGRATED CIRCUIT TESTING"		Rutten			(concurrent)
	AD						
	AE						
	AF						
	AG						
	AH						

FOREIGN PATENT DOCUMENTS

Examiner's Initials	Cite No.	Patent Number	Date	Country	Class	Sub-Class	Translation
21	AI	EP 0.755 071 A2	18 July 1996	Europe			Yes No
	AJ						
	AK						
	AL						
	AM						

Other (Include Author, Title, Date, Pertinent Pages, Etc.)

Examiner's Initials	Cite No.	Other (Include Author, Title, Date, Pertinent Pages, Etc.)
21	AN	"Introducing WOW Technology", http://www.formfactor.com/about/wow/wow_pg2.html
	AO	"Introducing WOW Technology", http://www.formfactor.com/about/wow/wow_pg5.html
	AP	"Focus on FormFactor", THE FINAL TEST REPORT, Vol. 12, No. 09, September 2001, Ikonix Corp. P.O. Box 1938, Lafayette, CA 94549-1938
	AQ	"Flip-Chip Bonding on 6-um Pitch using Thin-Film Microspring Technology", Donald L. Smith et al., Xerox Palo Alto Research Center, Proceedings, 48 th Electronic Components and Technology Conference, IEEE, May 1998.
	AR	

Examiner

[Signature]

Date Considered

5/4/09

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609;
Draw line through citation if not in conformance and not considered. Include a copy of this form with next communication to the Applicant.